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注記 NOTES

1. 使用材料 MATERIAL

ハウジング : 液晶ポリマー (LCP) UL94V-0 (黒)

60極品はLCPのグレードが異なります。

HOUSING: LIQUID CRYSTAL POLYMER UL94V-0 (COLOR: BLACK)

ターミナル : 銅合金

TERMINAL : COPPER ALLOY

金具 : 銅合金

FITTING NAIL : COPPER ALLOY

2. メッキ仕様 PLATING

ターミナル TERMINAL

金メッキ

GOLD

下地メッキ : ニッケルメッキ

UNDER PLATING : NICKEL

※コンタクト部とテール部はニッケルメッキによって分断されている金メッキです。

DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT AND THE TAIL PART BY THE NICKEL PLATING.

金具 FITTING NAIL

錫メッキ

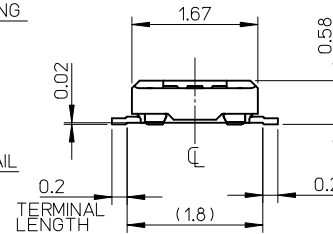
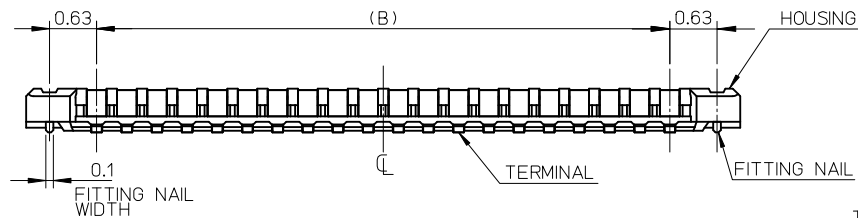
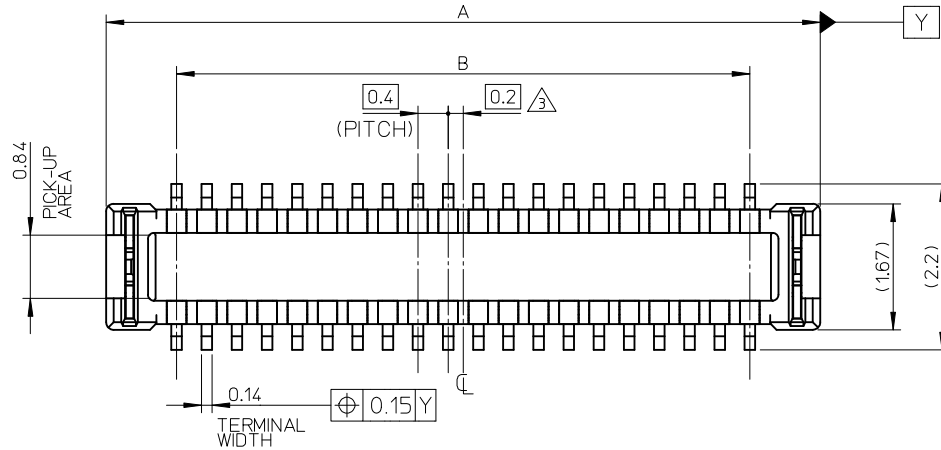
Tin PLATING

下地メッキ : ニッケルメッキ

UNDER PLATING : NICKEL

 $\Delta 3$ (全極数/2) = 偶数の場合に適用。
APPLY FOR (CIRCUIT/2) = EVEN.4. 嵌合相手 : 503304 シリーズ
MATE WITH : 503304 SERIES.

5. テール平坦度は、0.08 以下

テール及び金具の平坦度は、0.1 以下
TAIL COPLANARITY TO BE 0.08 MAXIMUM.
TAIL AND FITTING NAIL COPLANARITY
TO BE 0.1 MAXIMUM.

11.6	13.47	503308-6020	60
9.6	11.47	503308-5010	50
8.4	10.27	503308-4410	44
8.0	9.87	503308-4210	42
7.6	9.47	503308-4010	40
5.6	7.47	503308-3010	30
4.8	6.67	503308-2610	26
4.4	6.27	503308-2410	24
3.6	5.47	503308-2010	20
3.2	5.07	503308-1810	18
2.8	4.67	503308-1610	16
2.0	3.87	503308-1210	12
B	A	EMBOSSSED PACKAGE	極数
		オーダー番号 ORDER No.	CIRCUITS
		CONNECTOR SERIES No. : 503308-**09	

REVISED EC NO: J2011-0495 DRWN:MTAKAHASHI03/20/10/05/14 CHKD: 20/10/10/05 APPR:MSASAO 20/10/10/05	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 15:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION						
		10 UNDER	± 0.2	DRAWN BY KSASAKI	DATE 2008/04/17	TITLE 0.4 B-TO-B CONN. HGT=0.7 W=2.6 PLUG ASS'Y								
		10 OVER 30 UNDER	± 0.25	CHECKED BY THIRATA	DATE 2008/04/17									
		30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2008/04/17	MOLEX INCORPORATED								
		ANGULAR ±1 °		MATERIAL NO. SEE CHART							DOCUMENT NO. SD-503308-001		SHEET NO. 1 OF 2	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS												
	REV			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										

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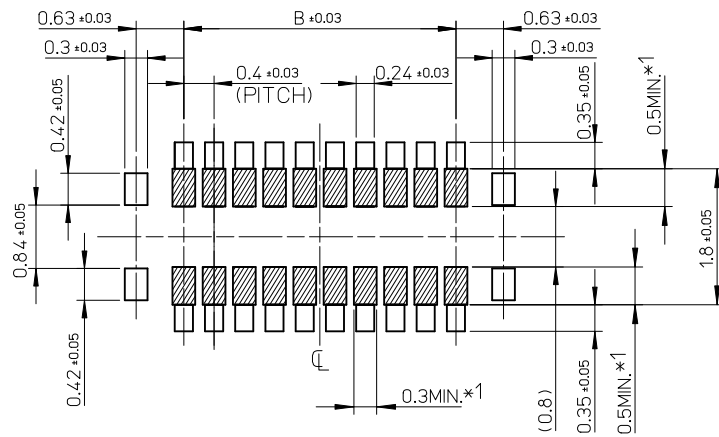
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*1 パターン引き回し、および半田禁止エリア
(当該箇所においては、これと接する回路以外の配線を禁止する。
また、接する回路を配線する場合はレジストを施し、この部分に
半田は無きこととする。)

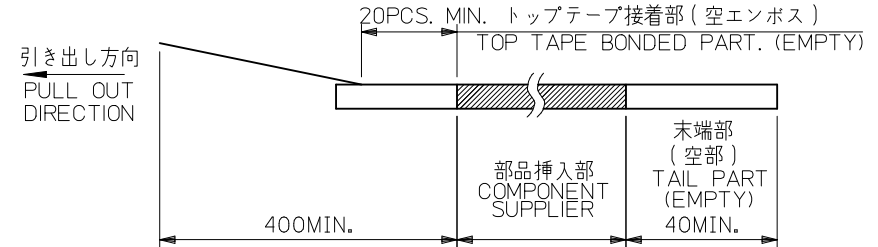
*1 PROHIBITED AREA OF PATTERN WIRING AND SOLDER.
(FOR EACH AREA, THE WIRING THAT TOUCHES ON THE SOLDER
CAN BE ATTACHED, THEN COVERED WITH A FILM TO KEEP SOLDER OUT.)

RECOMMENDED P.W. BOARD
PATTERN LAYOUT

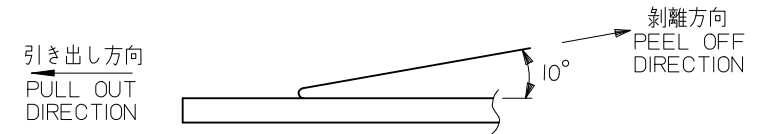
REVISED EC NO: J2011-0495 DRWN:MTAKAHASHI 03 2010/05/14 CHKD: 2010/10/05 APPR:MSASAO 2010/10/05	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 15:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				DRAWN BY DATE		TITLE 0.4 B-TO-B CONN. HGT=0.7 W=2.6 PLUG ASS'Y				
		10 UNDER ± 0.2		KSASAKI 2008/04/17						
		10 OVER 30 UNDER ± 0.25		CHECKED BY DATE						
				THIRATA 2008/04/17						
	30 OVER ± 0.3		APPROVED BY DATE							
			MSASAO 2008/04/17		MOLEX INCORPORATED					
REV	ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.				SHEET NO.	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-503308-001				2 OF 2	
			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

注記 NOTES

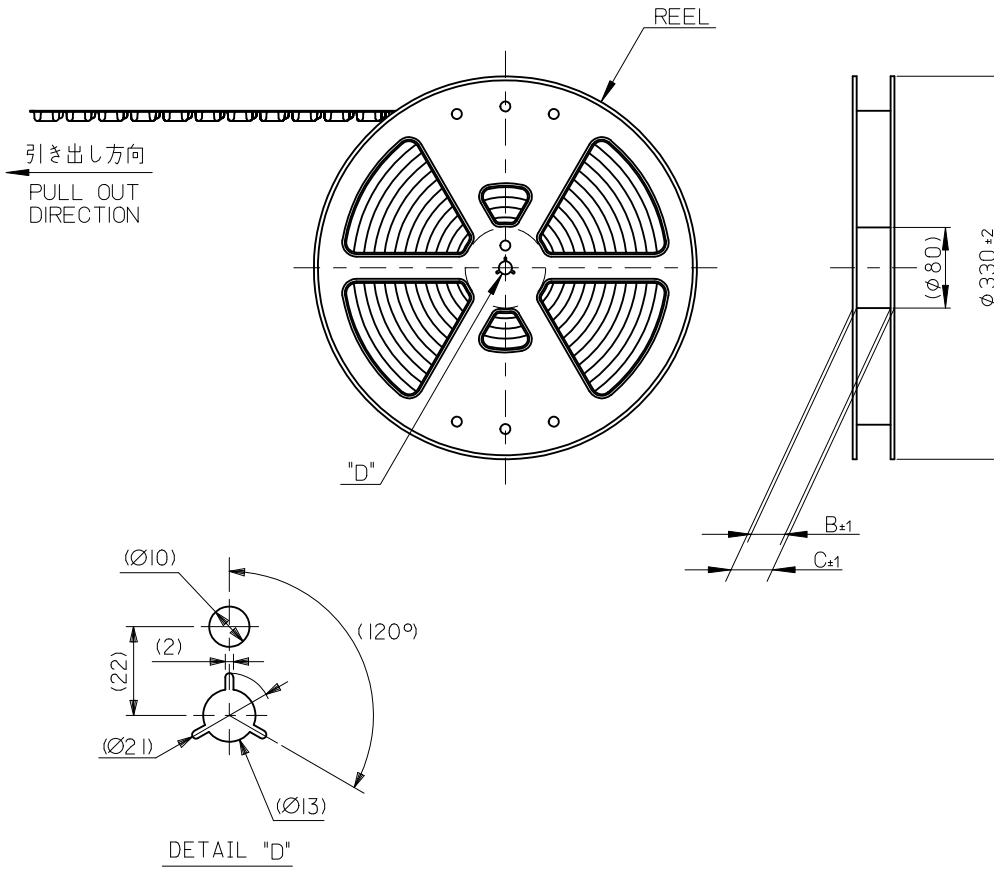
- 製品詳細寸法については製品単体図面を参照下さい。
RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
- 梱包数量 : 3000 個/リール
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度 : 0.1N~1.3N(10gf~130gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N~1.3N(10gf~130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTION.

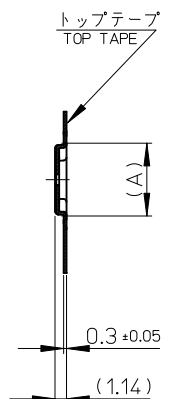


- 材料 MATERIAL
キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYRENE)
トップテープ (TOP TAPE) : PET , OTHER
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- ELV 及び RoHS適合品
ELV AND RoHS COMPLIANT

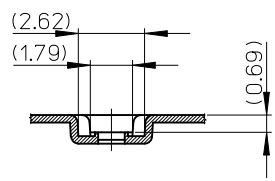
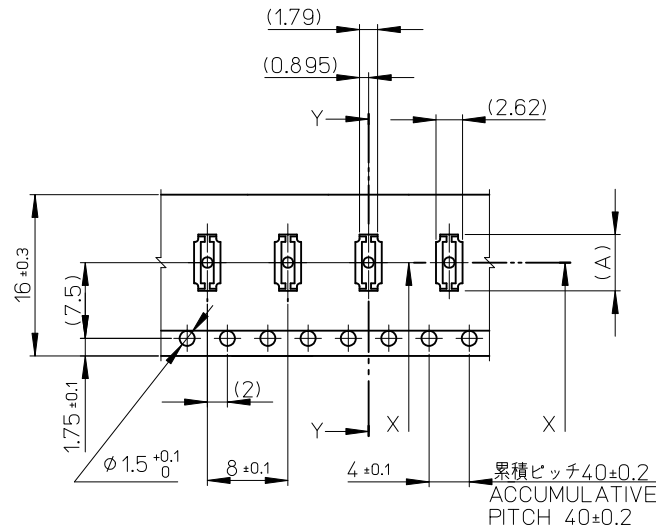


REVISIONS REV. NO. DATE BY CHKD. APPR. DESCRIPTION D 2010/08/16 DRWN:KSASAKI 2010/10/05 CHKD:MSASAO 2010/10/05 D 2011-04-95 D 2004/04/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	MODEL NO. 503308-**10
	10 UNDER	±0.2	DRAWN BY KSASAKI	DATE 2008/12/12	TITLE 0.4 B-TO-B CONN. HGT=0.7 PLUG ASSY EMBSTP PKG		
	10 OVER 30 UNDER	±0.25	CHECKED BY THIRATA	DATE 2008/12/12			
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 2008/12/12	MOLEX INCORPORATED		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	ANGULAR ±1 °		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-503308-002		
			SIZE A3		SHEET NO. 1 OF 3		

引き出し方向
PULL OUT DIRECTION



SECTION Y-Y



SECTION X-X

16mm 幅キャリアテープ
16mm WIDTH CARRIER TAPE

16	21.4	17.4	6.79	503308-2610		26
			6.39	503308-2410		24
			5.59	503308-2010		20
			5.19	503308-1810		18
			4.79	503308-1610		16
			3.99	503308-1210		12
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL No.		CKT.
				MODEL No.	503308-**-10	

REVISED

EC NO: J2011-0495

DRWN:KSASAKI

CHKD:MSASAO

APPR:MSASAO

2010/08/16

2010/10/05

2010/10/05

DESCRIPTION

REV

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER ± 0.2

10 OVER 30 UNDER ± 0.25

30 OVER ± 0.3

ANGULAR ± 1 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

DRAWN BY DATE

KSASAKI 2008/12/12

CHECKED BY DATE

THIRATA 2008/12/12

APPROVED BY DATE

MSASAO 2008/12/12

MATERIAL NO.

SEE CHART

SIZE

A3

SCALE

DESIGN UNITS

METRIC

THIRD ANGLE
PROJECTION

TITLE

0.4 B-TO-B CONN. HGT=0.7
PLUG ASSY EMBSTP PKG

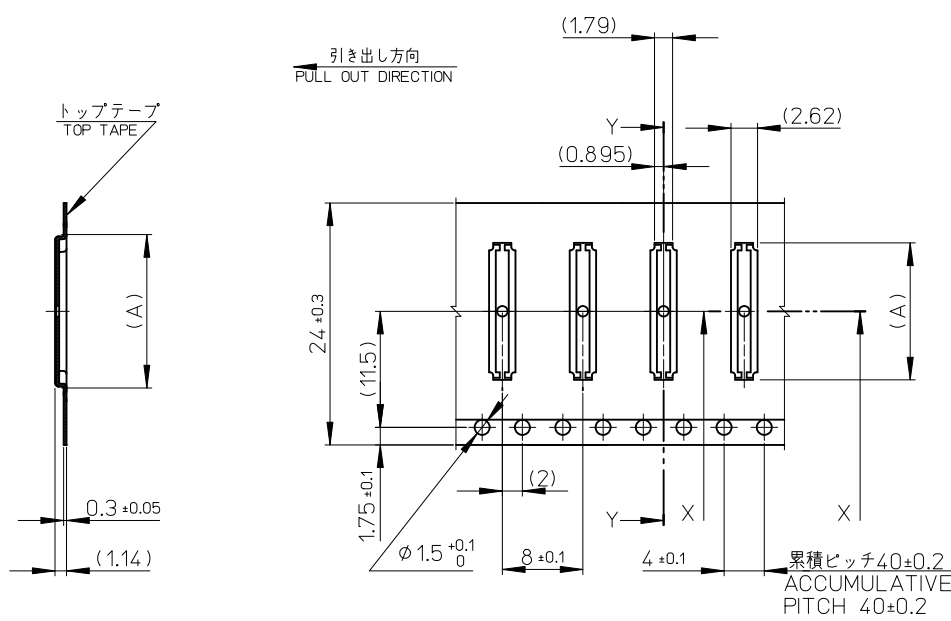
MOLEX INCORPORATED

DOCUMENT NO.

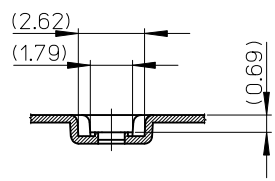
SD-503308-002

SHEET NO.

2 OF 3



SECTION Y-Y



SECTION X-X

24mm 幅キャリアテープ
24mm WIDTH CARRIER TAPE

24	29.4	25.4	13.59	503308-6020		60
			11.59	503308-5010		50
			10.39	503308-4410		44
			9.99	503308-4210		42
			9.59	503308-4010		40
			7.59	503308-3010		30
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL No.		CKT.
				MODEL No.	503308-***10	

REVISED EC NO: J2011-0495 DRWN:KSASAKI CHKD: APPR:MSASAO REV D	DESCRIPTION 2010/08/16 2010/10/05 2010/10/05	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	MODEL NO.	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY KSASAKI	DATE 2008/12/12	TITLE 0.4 B-TO-B CONN. HGT=0.7 PLUG ASSY EMBSTP PKG				
		10 OVER 30 UNDER	±0.25	CHECKED BY THIRATA	DATE 2008/12/12					
		30 OVER	±0.3	APPROVED BY MSASAO	DATE 2008/12/12	MOLEX MOLEX INCORPORATED				
		ANGULAR	±1 °	MATERIAL NO.	SEE CHART					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				